## Material Specifications

<table>
<thead>
<tr>
<th>Hot-side Temperature</th>
<th>Module Specifications</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Material Specifications (27 °C hot side temperature)</td>
</tr>
<tr>
<td></td>
<td>Vmax (V)</td>
</tr>
<tr>
<td></td>
<td>Imax (A)</td>
</tr>
<tr>
<td></td>
<td>Qmax (W)</td>
</tr>
<tr>
<td></td>
<td>DTmax (°C)</td>
</tr>
<tr>
<td>Operation/storage temperature</td>
<td>-40 °C to +80 °C</td>
</tr>
</tbody>
</table>

Module material specifications are nominal values based on the hot-side temperature indicated. Thermoelectric material parameter tolerance is +/-10%.

In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.

Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQ’s, and ordering information posted on our website before purchasing or using this product.

### Optional Features and Notes:

- **Width, A (mm)**: 40 ±0.5/-0.2
- **Width, B (mm)**: 40 ±0.5/-0.2
- **Height, H (mm)**: 3.4 ±0.05
- **Flatness, F (mm)**: 0.02
- **Parallelism, P (mm)**: 0.03
- **Wire Size, WS (mm²)**: 0.35
- **Wire Length, WL (mm)**: 120

Performance graphs include thermal resistance of substrates.

Add "P" to part number for sealing module with epoxy potting.
Unpotted HP-127-1.4-1.15-71 at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.
Potted HP-127-1.4-1.15-71 at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.
Unpotted HP-127-1.4-1.15-71 at a hot-side temperature of 50 °C
Potted HP-127-1.4-1.15-71 at a hot-side temperature of 50 °C
Unpotted HP-127-1.4-1.15-71 at a hot-side temperature of 70 °C
Potted HP-127-1.4-1.15-71 at a hot-side temperature of 70 °C